L Number	Hits	Search Text	DB	Time stamp
1	1	(rta or rapid near2 annealer).ti. and tube	USPAT;	2004/01/09 08:45
		and reactor	US-PGPUB; EPO; JPO;	
			DERWENT;	
		•	IBM_TDB	
2	220	(rta or rapid near thermal near anneal\$3)	USPAT;	2004/01/09 08:51
		and tube and reactor	US-PGPUB;	
	;		EPO; JPO; DERWENT;	
			IBM TDB	
3	302	· · · · · · · · · · · · · · · · · · ·	USPAT;	2004/01/09 08:51
		near5 (apparatus or housing)	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
4	282	(rta or rapid near thermal near anneal\$3)	USPAT;	2004/01/09 08:51
		near3 (apparatus)	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
5	42	(rta or rapid near thermal near anneal\$3)	USPAT;	2004/01/09 09:10
		near3 (apparatus) and tube	US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
6	22	(rta or rapid near thermal near anneal\$3 or	USPAT;	2004/01/09 09:14
		rtp) same tube same reactor	US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
7	29	reactor near2 (slot or opening) same (wafer	USPAT;	2004/01/09 09:16
		or substrate) near5 (position or positioning	US-PGPUB;	
		or positioned or alignment or align or	EPO; JPO;	
		aligning or locating or location)	DERWENT; IBM TDB	
_	17342	(rta or rtp or thermal near2 process\$3 or	USPAT;	2004/01/09 08:45
		heat near2 process\$3 or anneal or annealing	US-PGPUB;	
		or annealer) and (position or positioner or	EPO; JPO; DERWENT;	
		positioning or aligning or locating or locator or locater or positioned or	IBM TDB	
		placement or (distance or separation or	_	
		separator) near3 (lamp or heat or source or		
		light)) near5 (wafer or tray or holder or chuck or carrier or substrate)		
_	2066		USPAT;	2004/01/05 14:38
		heat near2 process\$3 or anneal or annealing	US-PGPUB;	
		or annealer) same (position or positioner or	EPO; JPO;	
		positioning or aligning or locating or locator or locater or positioned or	DERWENT; IBM TDB	
		placement or (distance or separation or		
		separator) near3 (lamp or heat or source or		
		light)) near5 (wafer or tray or holder or chuck or carrier or substrate)		
_	114	1	USPAT;	2004/01/05 14:42
		heat near2 process\$3 or anneal or annealing	US-PGPUB;	
		or annealer) same (position or positioner or	EPO; JPO;	
		positioning or aligning or locating or locator or locater or positioned or	DERWENT; IBM TDB	
		placement or (distance or separation or	I TEM TIDE	
		separator) near3 (lamp or heat or source or		
		light)) near5 (wafer or tray or holder or		
		chuck or carrier or substrate) near10 (groove or notch or c or guide or grooved or		
		notched)		
L	1 <u></u>	1		1

_	39	(rta or rtp or thermal near2 process\$3 or	USPAT;	2004/01/05 15:30
		heat near2 process\$3 or anneal or annealing	US-PGPUB;	
		or annealer) same (position or positioner or	EPO; JPO;	
	1	positioning or aligning or locating or	DERWENT;	
		locator or locater or positioned or	IBM_TDB	
		placement or (distance or separation or		
		separator) near3 (lamp or heat or source or		
	1	light)) near5 (wafer or tray or holder or		
		chuck or carrier or substrate) near10		
	:	(groove or notch or c near shape\$2 or guide		
		or grooved or notched)		÷
-	1035	(rta or rtp or rapid adj thermal).ti.	USPAT;	2004/01/05 15:30
			US-PGPUB;	
İ	ļ		EPO; JPO;	
			DERWENT;	
	114	(-the are returned and thermal) to and	IBM_TDB	2004/01/06 00:25
-	114		USPAT;	2004/01/06 09:25
		(position or positioning or locating or	US-PGPUB;	
		locator or positioner or groove or guide or	EPO; JPO; DERWENT;	
		distance or spacing) near4 (wafer or substrate or tray or holder or carrier or	IBM TDB	
		chuck)	TON-IDB	
_	4		USPAT;	2004/01/06 09:28
		fabrication or heating or coating or	US-PGPUB;	2001,01,00
		process) and (substrate or wafer) near2	EPO; JPO;	
		(holder or carrier or boat or chuck) near2	DERWENT;	
		(positioner or positioned or aligned or	IBM TDB	
		aligner or positioning or placement) near4		
		(groove or notch)	Į	
_	24	semiconductor and (substrate or wafer) near2	USPAT;	2004/01/06 09:30
İ	1	(holder or carrier or boat or chuck or tray)	US-PGPUB;	
		near2 (positioner or positioned or aligned	EPO; JPO;	
		or aligner or positioning or placement)	DERWENT;	
		near8 (groove or notch)	IBM_TDB	
_	92	semiconductor and (substrate or wafer) near2	USPAT;	2004/01/06 12:15
		(holder or carrier or boat or chuck or tray)	US-PGPUB;	
		near8 (positioner or positioned or aligned	EPO; JPO;	
		or aligner or positioning or placement)	DERWENT;	
		near8 (groove or notch)	IBM_TDB	
-	125	(+	USPAT;	2004/01/06 12:18
		carrier or boat or chuck or tray) near10	US-PGPUB;	
		(positioner or positioned or aligned or	EPO; JPO;	
		aligner or positioning or placement) near10	DERWENT;	
		(discrete or kit or attachable or detachable	IBM_TDB	
	576	or separate or nonintegral or non-integral) 257/E21.324.ccls.	USPAT;	2004/01/06 12:19
	5/6	237/121.321.0013.	US-PGPUB;	2004/01/00 12:19
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	78	257/E21.324.ccls. and (wafer or substrate)	USPAT;	2004/01/06 13:15
1	1	near6 (positioning or position or positioner	US-PGPUB;	
	]	or positioned or locator or placement or	EPO; JPO;	
		secured or alignment or aligning)	DERWENT;	
		J	IBM TDB	
<u> </u>	48	(wafer or substrate) near2 (tray or carrier	USPAT;	2004/01/06 13:25
1		or holder) near5 (inserting or insertion or	US-PGPUB;	
1		insert) near6 (groove or notch or guide or	EPO; JPO;	
i	ļ	guiding or grooved)	DERWENT;	
1			IBM_TDB	
-	166	438/663.ccls.	USPAT;	2004/01/06 13:25
			US-PGPUB;	
			EPO; JPO;	
1			DERWENT;	
	<u></u>		IBM_TDB	

	1 2 2 2		TTODAM	0004/01/05 15 05
_	183	<u> </u>	USPAT;	2004/01/07 16:35
		or diffusion or diffuser or rie or pecvd or	US-PGPUB;	
		chamber or tube) and (wafer or substrate)	EPO; JPO;	
		near4 (boat or tray or holder or carrier or	DERWENT;	
		chuck) near5 (insertion or insert or	IBM TDB	
		inserting or loading or loaded or load)		
		near10 (groove or grooved or track or guide		
		or guided or guiding)		
-	176	•	USPAT;	2004/01/08 10:11
		or diffusion or diffuser or rie or pecvd or	US-PGPUB;	
		chamber or tube) and (wafer or substrate)	EPO; JPO;	
		near3 (boat or tray or holder or carrier or	DERWENT;	
		chuck) near5 (insertion or insert or	IBM TDB	
		inserting or loading or loaded or load)		
		near10 (groove or grooved or track or guide		
		or guided or guiding or notch)		
-	2	5820367.pn.	USPAT;	2004/01/08 10:11
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	5	5820367.URPN.	USPAT	2004/01/08 10:11